

ABSTRACT

SUBSTRATE HAVING GATE SLOTS AND MOLDING DEVICE AND
MOLDING METHOD THEREOF

The invention relates to a substrate having gate slots for the flow of molding resin, and related molding device and molding method in which said substrate is used.

According to the invention, there is provided a substrate 10 having a multitude of chip pads 20 for mounting semiconductor chips, characterized in that gate slots 30 are formed along the resin routes 102 of the substrate 10 corresponding to the gate of mold 70, and said gate slots 30 extends from the edge of substrate 10 to the near part of the molded package 101.

And according to the invention, the molding device and molding methods which is properly use said gate slotted substrate 10 are provided.

Fig.4